



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2022-01-07
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Material Declaration champion	Representative Title	Material Declaration champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32G071KBU3	74MG*460XXB	A	998Z	2022-01-07
	Amount	UoM	Unit type	ST ECOPACK Grade
	48.75	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Tin (Sn), immersion	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	5x5x0.55	32	flat	
Comment	Package : A0B8 UFQFPN 5X5X0.55 32L 0.5 MM PITCH 8202208			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-17 Jan 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	74MG*460XXB				5999999.0	1000008.7
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	2.036	mg	supplier	die	Silicon (Si)	7440-21-3		1.839	mg	903242	37725
				supplier	metallization	Aluminium (Al)	7429-90-5		0.009	mg	4420	185
				supplier	metallization	Copper (Cu)	7440-50-8		0.084	mg	41257	1723
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.027	mg	13261	554
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	491	21
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	491	21
				supplier	Passivation	Silicon Nitride	12033-89-5		0.021	mg	10314	431
				supplier	Passivation	Silicon Oxide	7631-86-9		0.054	mg	26523	1108
				supplier	Metals	Silver	7440-22-4		0.592	mg	855000	12144
				Die Attach Epoxy_8290_Henkel	M-011 Other inorganic materials	0.692	mg	Supplier	Plastics/polymers	Epoxy resin 1	Trade Secret	
Supplier	Organic Compounds	Epoxy resin 2	Trade Secret						0.014	mg	20000	284
Supplier	Organic Compounds	.gamma.-Butyrolactone	96-48-0						0.021	mg	30000	426
Supplier	Organic Compounds	Epoxy resin 3	Trade Secret						0.014	mg	20000	284
Supplier	Organic Compounds	Amine	Trade Secret						0.014	mg	20000	284
Supplier	Metallic compounds	Copper oxide	1317-38-0						0.021	mg	30000	426
Supplier	Organic Compounds	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8						0.003	mg	5000	71
Supplier	Organic Compounds	Epoxy Resin A	Trade Secret						0.351	mg	21000	7207
Supplier	Organic Compounds	Epoxy Resin B	Trade Secret						0.351	mg	21000	7207
Supplier	Organic Compounds	Phenol Resin A	Trade Secret						0.351	mg	21000	7207
Mold Compound_EME-G770_Sumitomo	M-011 Other inorganic materials	16.730	mg	Supplier	Glass	Silica(Amorphous)A	60676-86-0		13.057	mg	780450	267842
				Supplier	Glass	Silica(Amorphous)B	7631-86-9		1.929	mg	115320	39577
				Supplier	Organic Compounds	Carbon Black	1333-86-4		0.104	mg	6230	2138
				Supplier	Metallic compounds	Metal Hydroxide	Trade Secret		0.234	mg	14000	4805
				Supplier	Organic Compounds	Phenol Resin B	Trade Secret		0.351	mg	21000	7207
				Supplier	Metals	Gold	7440-57-5		0.371	mg	1000000	7608
				Supplier	Metals	Tin	7440-31-5		0.719	mg	1000000	14748
				Supplier	Metals	Copper	7440-50-8		25.863	mg	917140	530559
				Supplier	Metals	Nickel	7440-02-0		0.635	mg	22500	13016
				Supplier	Metals	Silicon	7440-21-3		0.073	mg	2600	1504
GOLD WIRE AU 0.8MIL HA3 EN _HERA	Bonding Wire	0.371	mg	Supplier	Metals	Gold	7440-57-5		0.371	mg	1000000	7608
				Supplier	Metals	Tin	7440-31-5		0.719	mg	1000000	14748
				Supplier	Metals	Copper	7440-50-8		25.863	mg	917140	530559
Plating anode_Pure Tin_ASAHI	M-011 Other inorganic materials	0.719	mg	Supplier	Metals	Tin	7440-31-5		0.719	mg	1000000	14748
				Supplier	Metals	Copper	7440-50-8		25.863	mg	917140	530559
				Supplier	Metals	Nickel	7440-02-0		0.635	mg	22500	13016
Leadframe_C7025+AG_HDS	Copper & its alloys	28.200	mg	Supplier	Metals	Silicon	7440-21-3		0.073	mg	2600	1504
				Supplier	Metals	Magnesium	7439-95-4		0.032	mg	1150	665
				Supplier	Metals	Silver	7440-22-4		1.596	mg	56610	32748